

# STS17NH3LL

# N-channel 30 V - 0.004 Ω - 17 A - SO-8 STripFET™ Power MOSFET for DC-DC conversion

#### **Features**

Туре	V <sub>DSS</sub>	R <sub>DS(on)</sub>	I <sub>D</sub>
STS17NH3LL	30V	<0.0057Ω	17A <sup>(1)</sup>

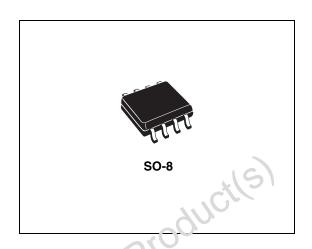
- 1. This value is rated according to Rthj-pcb
- Optimal R<sub>DS(on)</sub> x Qg trade-off @ 4.5 V
- Conduction losses reduced
- Improved junction-case thermal resistance
- Low threshold device

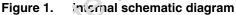
#### **Applications**

■ Switching application

## **Description**

This device utilizes the latest advanced design rules of ST's proprietary STripFET™ technology. This process coupled to unique metallization techniques realizes the most advanced low voltage Power MOSFET in SO-8 ever produced.





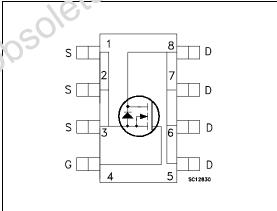


Table Device summary

Order code	Marking	Package	Packaging
STS17NH3LL	17H3LL-	SO-8	Tape & reel

December 2007 Rev 3 1/12

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STS17NH3LL Electrical ratings

# 1 Electrical ratings

Table 2. Absolute maximum ratings

Symbol	Parameter	Value	Unit	
$V_{DS}$	Drain-source voltage (V <sub>GS</sub> = 0)	30	V	
$V_{GS}$	Gate- source voltage	± 16	V	
I <sub>D</sub> <sup>(1)</sup>	Drain current (continuous) at T <sub>C</sub> = 25°C	17	Α	
I <sub>D</sub>	Drain current (continuous) at T <sub>C</sub> = 100°C	10.6	Α	
I <sub>DM</sub> <sup>(2)</sup>	Drain current (pulsed)	68	Α	
P <sub>tot</sub> <sup>(1)</sup>	Total dissipation at T <sub>C</sub> = 25°C	2.7	W	
T <sub>stg</sub>	Storage temperature	-55 to 150	°C	
Tj	Operating junction temperature	-55 to 150		

<sup>1.</sup> This value is rated according to Rthj-pcb

Table 3. Thermal resistance

Symbol	Parameter		Value	Unit
Rthj-pcb <sup>(1)</sup>	Thermal resistance junction-ambient max	76	47	°C/W

<sup>1.</sup> When mounted on 1inch<sup>2</sup> FR-4 board, 2oz of Cu and t< 10sec

Table 4. Avalanche data

	Symbol Parameter		Value	Unit
	I <sub>AV</sub>	Not-repetitive avalanche current	7.5	Α
	E <sub>AS</sub>	Single pulse avalanche energy (starting Tj=25°C, Id=I <sub>AV</sub> )	150	mJ
Obsolei	ePr			

<sup>2.</sup> Pulse width limited by safe operating area

Electrical characteristics STS17NH3LL

# 2 Electrical characteristics

(T<sub>CASE</sub>=25°C unless otherwise specified)

Table 5. On/off states

Symbol	Parameter	Test conditions	Min	Тур.	Max	Unit
V <sub>(BR)DSS</sub>	Drain-source breakdown voltage	$I_D = 250 \mu A, V_{GS} = 0$	30			٧
I <sub>DSS</sub>	Zero gate voltage drain current (V <sub>GS</sub> = 0)	$V_{DS}$ = Max rating $V_{DS}$ = Max rating @125°C			1 10	μ <b>Α</b> μ <b>Α</b>
I <sub>GSS</sub>	Gate-body leakage current (V <sub>DS</sub> = 0)	V <sub>GS</sub> = ± 16 V			±100	nA
V <sub>GS(th)</sub>	Gate threshold voltage	$V_{DS} = V_{GS}, I_{D} = 250 \mu A$	1			V
R <sub>DS(on)</sub>	Static drain-source on resistance	$V_{GS} = 10 \text{ V}, I_D = 8.5 \text{ A}$ $V_{GS} = 4.5 \text{ V}, I_D = 8.5 \text{ A}$		0.004 0.005	0.0057 0.0075	$\Omega$ $\Omega$

Table 6. Dynamic

	Symbol	Parameter	Test conditions	Min	Тур.	Max	Unit
	$C_{iss}$ $C_{oss}$ $C_{rss}$	Input capacitance Output capacitance Reverse transfer capacitance	V <sub>DS</sub> =25 V, f=1 MHz V <sub>GS</sub> = 0		1810 565 41		pF pF pF
	$egin{array}{c} Q_{ m g} \ Q_{ m gd} \end{array}$	Total gate charge Gate-source charge Gate-drain charge	$V_{DD}$ =15 V, $I_{D}$ =17 A $V_{GS}$ =4.5 V (see Figure 14)		18 4.8 5.3	24	nC nC nC
	$R_{G}$	Gate input resistance	f=1 MHz Gate DC Bias = 0 Test signal level = 20 mV open drain	0.5	1.5	3	Ω
Obsole	ReP	,OO.					

Table 7. **Switching times** 

Symbol	Parameter	Test conditions	Min	Тур.	Max	Unit
t <sub>d(on)</sub> t <sub>r</sub>	Turn-on delay time Rise time	$V_{DD}$ = 15 V, $I_D$ = 8.5 A $R_G$ = 4.7 $\Omega$ , $V_{GS}$ = 10 V (see Figure 16)		8 65		ns ns
t <sub>d(off)</sub>	Turn-off delay time Fall time	$V_{DD}$ = 15 V, $I_D$ = 8.5 A $R_G$ = 4.7 $\Omega$ , $V_{GS}$ = 10 V (see Figure 16)		38 20		ns ns

Table 8. Source drain diode

Symbol	Parameter	Test conditions	Min	Тур.	Max	Unit	
I <sub>SD</sub>	Source-drain current Source-drain current (pulsed)				17 68	A A	
V <sub>SD</sub> <sup>(1)</sup>	Forward on voltage	I <sub>SD</sub> = 17 A, V <sub>GS</sub> = 0			1.3	V	
t <sub>rr</sub> Q <sub>rr</sub> I <sub>RRM</sub>	Reverse recovery time Reverse recovery charge Reverse recovery current	$I_{SD}$ = 17 A, di/dt = 100 A/ $\mu$ s $V_{DD}$ = 15 V, T $_{j}$ = 25°C (see Figure 15)	000	22 32 1.9		ns nC A	
1. Pulsed: pulse duration=300µs, duty cycle 1.5%							

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Electrical characteristics STS17NH3LL

# 2.1 Electrical characteristics (curves)

Figure 2. Safe operating area

Figure 3. Thermal impedance

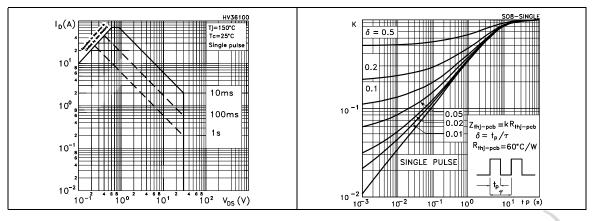


Figure 4. Output characteristics

Figure 5. Transfer characteristics

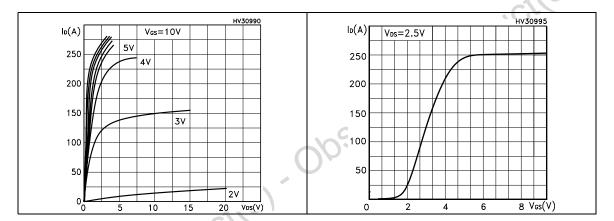


Figure 6. Normalized B<sub>VDSS</sub> vs temperature

Figure 7. Static drain-source on resistance

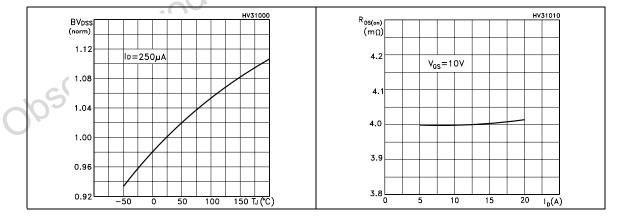


Figure 8. Gate charge vs gate-source voltage Figure 9. Capacitance variations

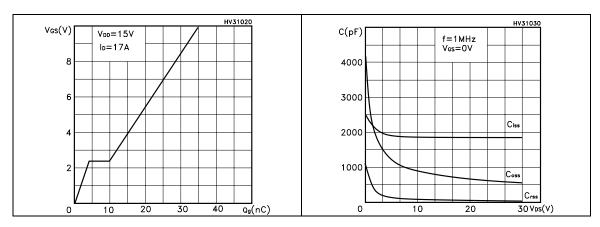


Figure 10. Normalized gate threshold voltage vs temperature

Figure 11. Normalized on resistance vs temperature

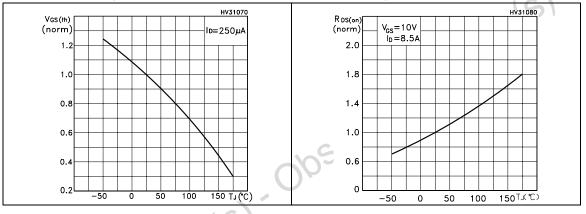
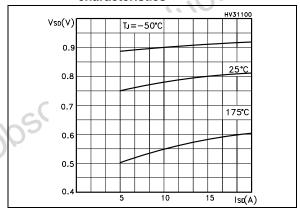


Figure 12. Source-drain diode forward characteristics



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Test circuit STS17NH3LL

# 3 Test circuit

Figure 13. Switching times test circuit for resistive load

Figure 14. Gate charge test circuit

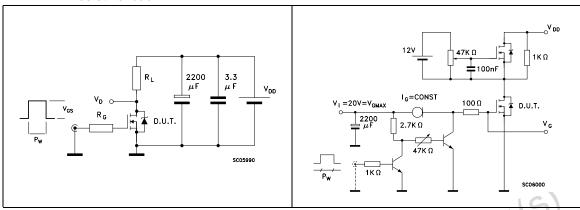


Figure 15. Test circuit for inductive load switching and diode recovery times

Figure 16. Unclamped inductive load test circuit

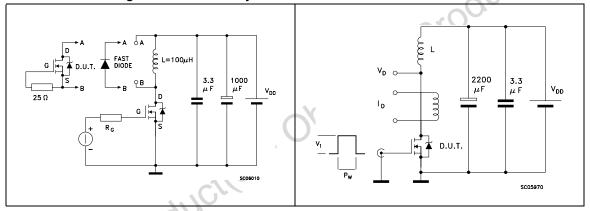
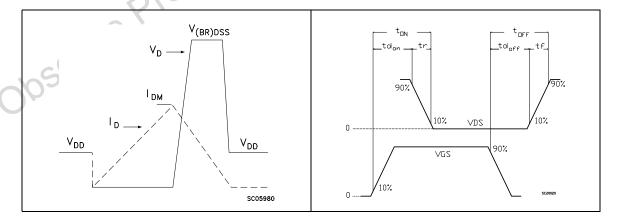


Figure 17. Unclamped inductive waveform

Figure 18. Switching time waveform



# 4 Package mechanical data

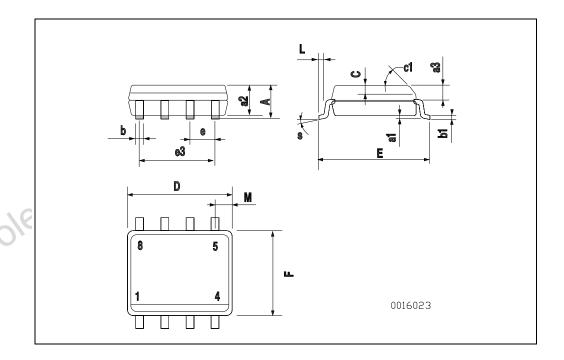
In order to meet environmental requirements, ST offers these devices in ECOPACK® packages. These packages have a lead-free second level interconnect. The category of second level interconnect is marked on the package and on the inner box label, in compliance with JEDEC Standard JESD97. The maximum ratings related to soldering conditions are also marked on the inner box label. ECOPACK is an ST trademark. ECOPACK specifications are available at: <a href="https://www.st.com">www.st.com</a>

Obsolete Product(s). Obsolete Product(s)

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#### **SO-8 MECHANICAL DATA**

DIM		mm.			inch	
DIM.	MIN.	TYP	MAX.	MIN.	TYP.	MAX.
Α			1.75			0.068
a1	0.1		0.25	0.003		0.009
a2			1.65			0.064
аЗ	0.65		0.85	0.025		0.033
b	0.35		0.48	0.013		0.018
b1	0.19		0.25	0.007		0.010
С	0.25		0.5	0.010		0.019
c1			45	(typ.)		•
D	4.8		5.0	0.188		0.196
Е	5.8		6.2	0.228		0.244
е		1.27			0.050	
е3		3.81			0.150	
F	3.8		4.0	0.14		0.157
L	0.4		1.27	0.015		0.050
М			0.6			0.023
S			8 (r	nax.)	•	•



STS17NH3LL Revision history

# 5 Revision history

Table 9. Document revision history

Date	Revision	Changes
01-Aug-2006	1	First release
09-Jan-2007	2	Complete version
12-Dec-2007	3	Inserted new Table 4: Avalanche data



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